PTO/SB08A(10-01)
Approved for use through 10/31/2002, Okig 851-0031
US Patient & Tradement Office U.S. DEPARTMENT OF COMMERCE
and information unless it investigate a uniformatic providers.

Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Under the Paperwork Reduction Act of 1995, no persons are nequired to respond to a collection of information unless it contains a valid OMB control number. Complete if Known			
	Application Number	Unknown 10/775, 890		
	Filing Date	Even Date Herewith		
	First Named Inventor	Sur, Biswajit		
	Group Art Unit	Unknown		
	Examiner Name	Unknown		
Sheet 1 of 1	Attorney Docket No: 884.319US2			

US PATENT DOCUMENTS							
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate	
ah	US-4,561,011	12/24/1985	Kohara, Masanobu, et al.	356	81	09/22/1983	
T_{-}	US-4,827,376	05/02/1989	Voss, Scott V.	361	388	12/18/1987	
	US-5,098,609	03/24/1992	Iruvanti, S., et al.	252	511	11/03/1989	
	US-5,276,289	01/04/1994	Satoh, R., et al.	174	260	03/25/1991	
	US-5,396,403	03/07/1995	Patel, C.	361	705	07/06/1993	
	US-5,587,882	12/24/1996	Patel, C.	361	705	08/30/1995	
	US-5,623,394	04/22/1997	Sherif, R. A., et al.	361	705	08/02/1996	
	US-5,672,548	09/30/1997	Culnane, T. M., et al.	437	209	06/26/1996	
7	US-5,744,863	04/28/1998	Culnane, T. M., et al.	257	712	06/07/1995	
	US-5,880,524	03/09/1999	Xie, Hong	257	704	05/05/1997	
	US-5,905,636	05/18/1999	Baska, D. A., et al.	361	705	01/23/1998	
	US-6,091,603	07/18/2000	Daves, Glenn G., et al.	361	704	09/30/1999	
	US-6,218,730	04/17/2001	Toy, Hiton T., et al.	257	704	01/06/1999	
	US-6,281,573	08/28/2001	Atwood, E. R., et al.	257	706	03/31/1998	
	US-6,292,369	09/18/2001	Daves, Glenn G., et al.	361	719	08/07/2000	
	US-6,294,408	09/25/2001	Edwards, David L., et al.	438	121	09/30/1999	
ah	US-6,372,337	04/16/2002	Takahashi, Takayuki, et al.	428	328	05/26/1999	

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T²
L	JP-03142860	06/18/1991	Tetsuya, H.	H01L	23/02	

	OTHE	R DOCUMENTS NON PATENT LITERATURE DOCUMENTS	
Examiner Initials*	Cite No 1	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T
a		AMENDOLA, A., et al., "Cooling Structure for an Integrated Circuit Module", IBM Technical Disclosure Bulletin, Vol. 23, No. 2, XP002191051, (July 1980),602	
α	-	HAYASHIDA, TETSUYA, "Manufacture of Semiconductor integrated circuit device", Patent Abstracts of Japan, Vol. 015, No. 365 (E-1111), (09 13 1991),	
ah		MILLER, R. C., "Structure for achieving thermal enhancement in a semiconductor package", <u>IBM Technical Dislosure Bulletin, Vol. 23, No. 6, XP002191052</u> , (Nov 1980),2308	

EXAMINER	andy Muy 2	DATE CONSIDERED	10/15/	04